



LSHM-120-04.0-L-DV-A-N-K-TR

**LSHM-DV SERIES** 

# HIGH-SPEED HERMAPHRODITIC ST

## **SPECIFICATIONS**

(0.50 mm) .0197"

For complete specifications and recommended PCB layouts see www.samtec.com?LSHM

Insulator Material:

Black Liquid Crystal Polymer Contact Material: Phosphor Bronze Plating: Au or Sn over 50 μ" (1.27 μm) Ni Current Rating:

2.0 A per pin (2 adjacent pins powered) Operating Temp Range: -55 °C to +125 °C RoHS Compliant:

## **PROCESSING**

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max Board Stacking:

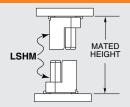
For applications requiring two or more connectors per board, contact ipg@samtec.com

# RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



# APPLICATION



LEAD STYLE	MATED HEIGHT*
-02.5 & -02.5	(5.00) .196
-02.5 & -03.0	(5.50) .217
-03.0 & -03.0	(6.00) .236
-02.5 & -04.0	(6.50) .256
-03.0 & -04.0	(7.00) .276
-04.0 & -04.0	(8.00) .315
-02.5 & -06.0	(8.50) .335
-03.0 & -06.0	(9.00) .354
-04.0 & -06.0	(10.00) .394
-06.0 & -06.0	, ,
*Processing conditions will affect mated height.	

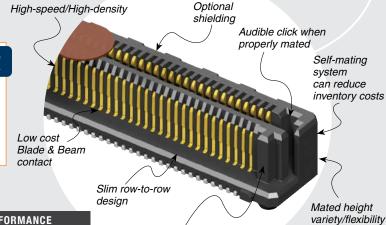
Note: Some lengths, styles and options are non-standard, non-returnable.

#### **Board Mates:**

Cable Mates:

LSHM





Vertical orientation

(right-angle available)

### HIGH-SPEED CHANNEL PERFORMANCE

LSHM-DV/LSHM-DV @ 5 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

**NO. PINS** 

**PER ROW** 

**PLATING OPTION** 

OPTION

SHIELD **OPTION** 







05, 10, 20, 30, 40, 50

Specify LEAD STYLE from chart

**LEAD** 

STYLE

= Gold flash on contact, Matte Tin on tail

=10 μ" (0.25 µm) Gold on contact, Matte Tin on tail

-DV = Vertical

-S = With Shield -N = Without Shield

= (3.50 mm) .138" DIA Polyimide film Pick & Place Pad

> -TR = Tape & Reel

